

January 14, 2001

To: Commissioner of Patents and Trademarks
Washington, D.C. 20231

Fr: George O. Saile Reg. No. 19,572
20 McIntosh Drive
Poughkeepsie, N.Y. 12603

Subject:

Divisional Patent Application of

Serial No.: 09261,681 3/3/99

GEORGE WONG

**A FILL PATTERN IN KERF AREAS TO PREVENT
LOCALIZED NON-UNIFORMITIES OF INSULATING
LAYERS AT DIE CORNERS ON SEMICONDUCTOR
SUBSTRATES**

PRELIMINARY AMENDMENT

Dear Sir:

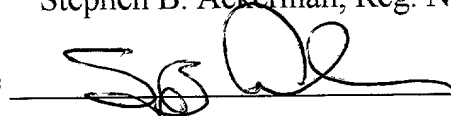
This is a preliminary amendment for the above referenced Divisional Patent
Application. Please amend the above identified application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States
Postal Service as first class mail in an envelope addressed to: Commissioner of Patents
and Trademarks, Washington, D.C. 20231, on January 16, 2001.

Stephen B. Ackerman, Reg. No. 37,761

Signature/Date



1/16/01

PLEASE AMEND THE SPECIFICATION AS FOLLOWS:

After the title, insert -- This is a division of Patent Application serial number 09261,681, filing date 3/3/99, A Fill Pattern In Kerf Areas To Prevent Localized Non-Uniformities Of Insulating Layers At Die Corners On Semiconductor Substrates, assigned to the same assignee as the present invention.

REMARKS

A reference to the parent case has been added by Preliminary Amendment to this Divisional Patent Application.

The application is believed to be in condition for allowance. Allowance of the subject Patent Application is therefore respectfully requested.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'SBA', with a stylized flourish extending to the right.

STEPHEN B. ACKERMAN, REG. NO. 37,761